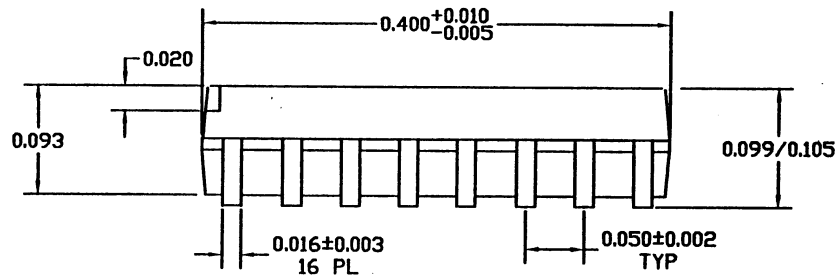
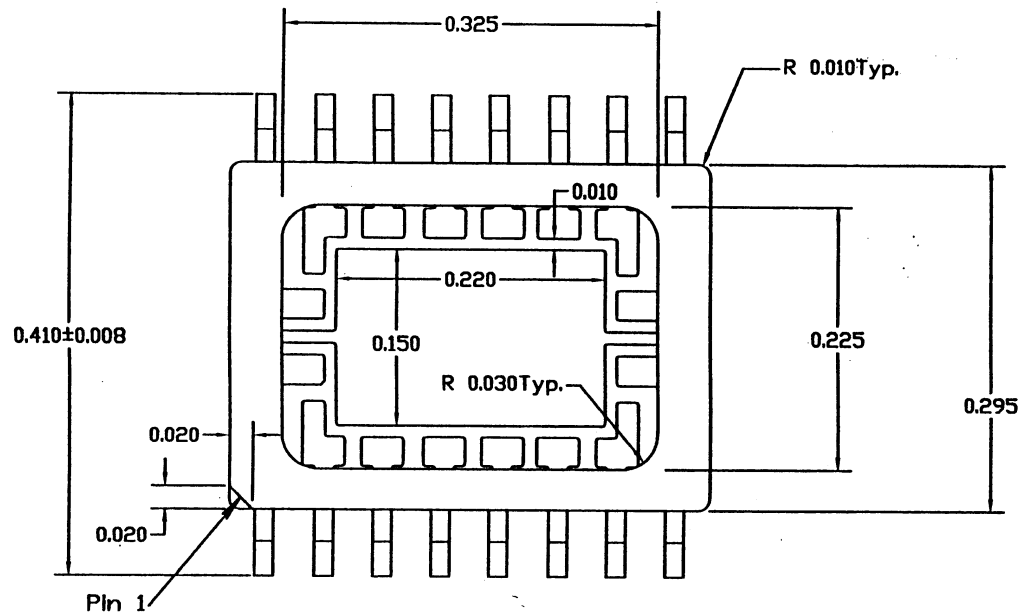
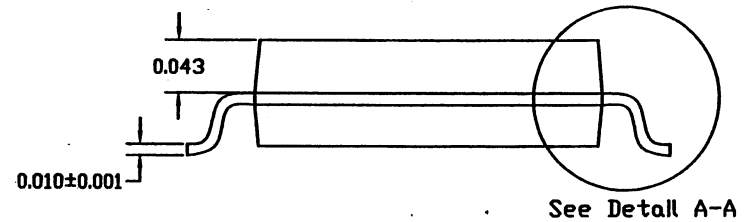
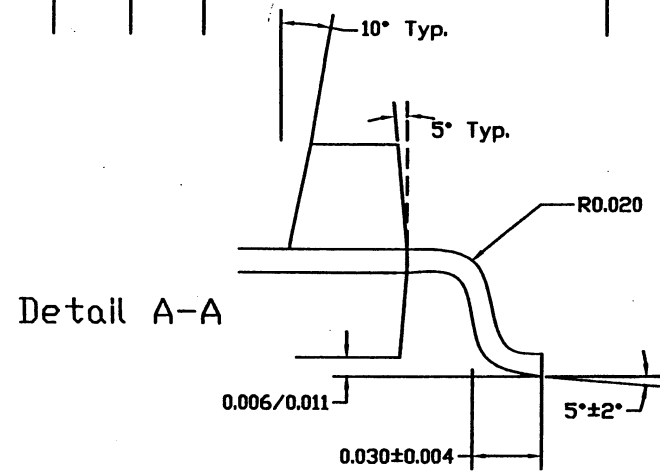


ECN	REV.	DESCRIPTION	DATE	APP'D
10026	1	PRODUCTION RELEASE	5/31/02	BF



NOTES:
 BODY : Plastic, Semiconductor Grade
 LEAD FRAME : Copper, 01in 194
 LEAD FINISH : 50 uIN Au, Over 50uIN NI
 DIE PAD : 0.220' x 0.150'



TITLE: 16 Lead SOIC Open-Pak™ (.300" Wide)			
MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: SD	
GEN. TOL: ±.005	DATE: 5/20/02	APP'D: BF 5/20/02	
SSH P/N PS0161502	DWG. NO. SOIC16-DP-02	REV. 1	